



600V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	RDS(ON) Max	I _D T _A = +25°C	
-600V	13Ω @ V _{GS} = -10V	-0.25A	

Description and Applications

This MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high-efficiency power management applications.

- Motor Control
- Backlighting
- AC-DC Converters

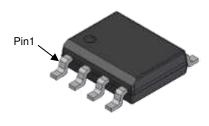
Features and Benefits

- Low On-Resistance
- High BV_{DSS} Rating for Power Application
- Low Input Capacitance
- Fast Switching
- High Efficiency
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

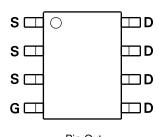
Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.076 grams (Approximate)

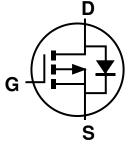
SO-8 (Standard B)



Top View



Pin-Out Top View



Equivalent Circuit

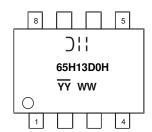
Ordering Information (Note 4)

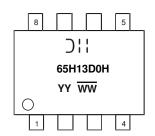
Part Number	Case	Packaging
DMP65H13D0HSS-13	SO-8 (Standard B)	4,000 / Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information





O!! = Manufacturer's Marking
65H13D0H = Product Type Marking Code
YYWW or YYWW = Date Code Marking
YY or YY = Year (ex: 21 = 2021)
WW or WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage(Note 5)		V _{DSS}	-600	V
Gate-Source Voltage		Vgss	±30	V
Continuous Drain Current (Note 6) V _{GS} = -10V	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	l _D	-0.25 -0.20	А
Maximum Body Diode Forward Current (Note 6)	T _A = +25°C T _A = +70°C	ls	-0.25 -0.20	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	l _{DM}	-2	Α	
Pulsed Source Current (10μs Pulse, Duty Cycle = 1%)		I _{SM}	-2	Α
Peak Diode Recovery dv/dt (Note 8)		dv/dt	5	V/ns

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation, @T _A = +25°C (Note 6)	PD	1.9	W
Thermal Resistance, Junction to Ambient @TA = +25°C (Note 6)	R _{0JA}	65	°C/W
Power Dissipation, @T _A = +25°C (Note 7)	PD	1.25	W
Thermal Resistance, Junction to Ambient @TA = +25°C (Note 7)	Reja	100	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

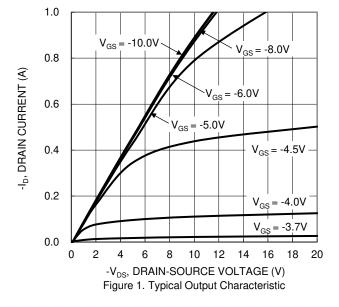
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BVDSS	-650	_	_	V	$V_{GS} = 0V, I_{D} = -250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	-1	μΑ	V _{DS} = -650V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	100	nA	$V_{GS} = \pm 30V$, $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V _{GS(TH)}	-2	-3	-4	V	$V_{DS} = V_{GS}$, $I_D = -250 \mu A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	10.5	13	Ω	$V_{GS} = -10V, I_D = -0.25A$	
Diode Forward Voltage	V _{SD}	_	-0.7	-1.3	V	V _{GS} = 0V, I _S = -0.25A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	1	582	_		$V_{DS} = -25V$, $f = 1MHz$, $V_{GS} = 0V$	
Output Capacitance	Coss	_	45	_	pF		
Reverse Transfer Capacitance	C _{rss}	_	3.3	_			
Gate Resistance	Rg	_	12.7	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge	Q_g	-	13.4	_		V _{DD} =-520V, I _D = -0.25A,	
Gate-Source Charge	Qgs	_	2	_	nC		
Gate-Drain Charge	Qgd	_	4.9	_		$V_{GS} = -10V$	
Turn-On Delay Time	tD(ON)	_	16	_		$V_{DD} = -325V, V_{GS} = -10V,$ $R_{G} = 3\Omega, I_{D} = -0.25A$	
Turn-On Rise Time	t _R	_	10	_	no		
Turn-Off Delay Time	tD(OFF)	_	44	_	ns		
Turn-Off Fall Time	tF		85	_			
Body Diode Reverse Recovery Time	trr	_	160	_	ns	la 1A dl/dt 100A/ug	
Body Diode Reverse Recovery Charge	Q _{RR}		1	_	μC Is = -1A, dI/dt = 100A/ μ s		

Notes:

- 5. HTRB V_{DS} maximum is -480V.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square pad layout.
- 7. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 8. Guaranteed by design. Not subject to production testing.
- 9. Short duration pulse test used to minimize self-heating effect.





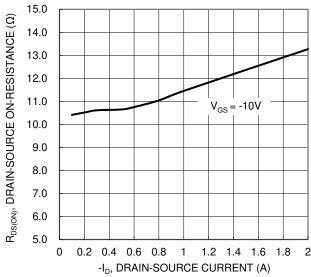


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

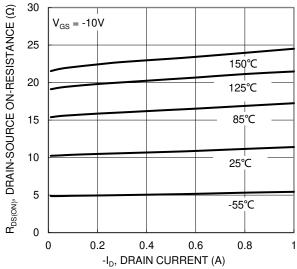
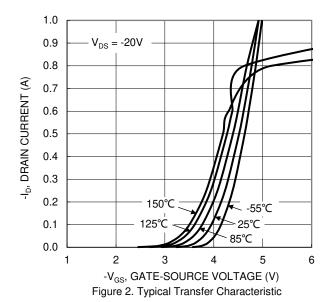
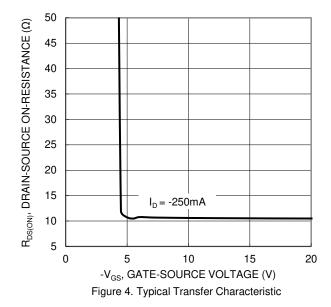


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





3 R_{DS(ON)}, DRAIN-SOURCE ON-RESISTANCE (NORMALIZED) 2.5 2 1.5 1 $V_{GS} = -10V, I_{D} = -250mA$ 0.5 0 -50 -25 0 25 50 75 100 125 150 T_{,I}, JUNCTION TEMPERATURE (°C)

Figure 6. On-Resistance Variation with Temperature



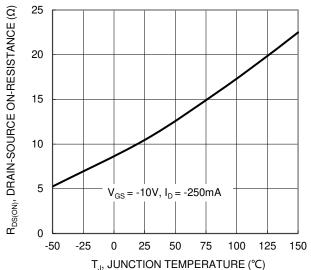


Figure 7. On-Resistance Variation with Temperature

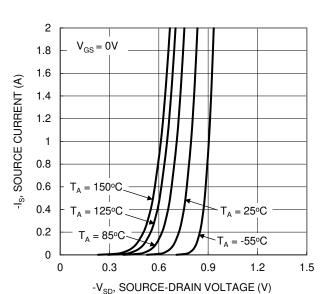


Figure 9. Diode Forward Voltage vs. Current

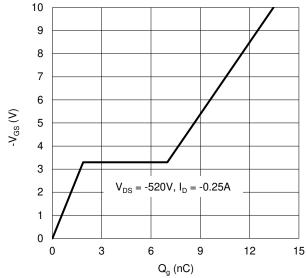


Figure 11. Gate Charge

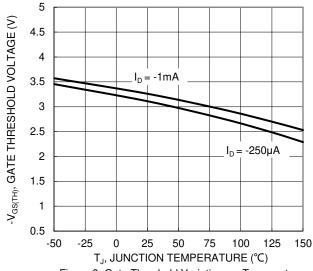


Figure 8. Gate Threshold Variation vs. Temperature

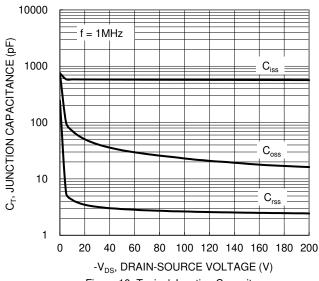


Figure 10. Typical Junction Capacitance

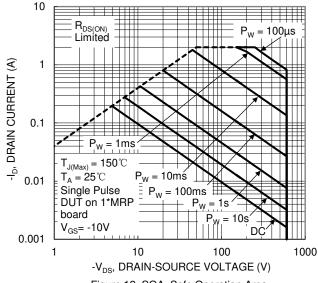


Figure 12. SOA, Safe Operation Area



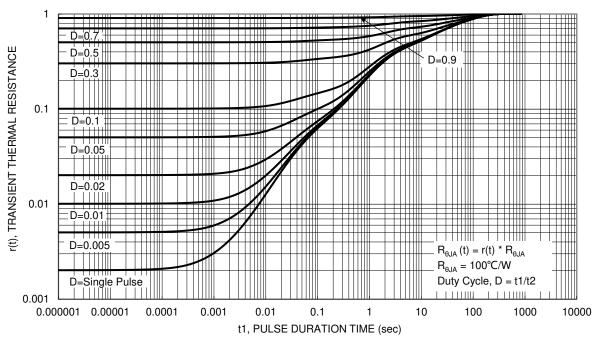


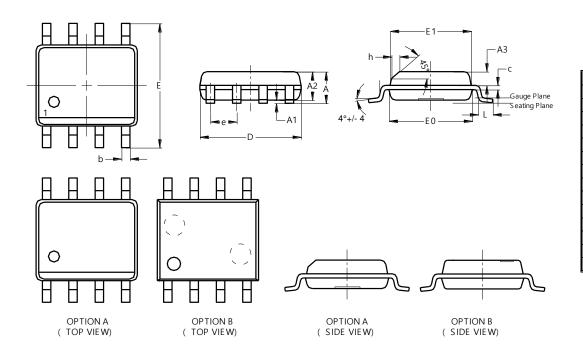
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Standard B)

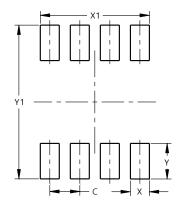


SO-8 (Standard B)				
Dim	Min	Max	Тур	
Α	1.35	1.75	1.45	
A 1	0.10	0.25	0.15	
A3	0.60	0.70	0.65	
b	0.30	0.51	0.40	
С	0.15	0.25	0.20	
D	4.70	5.10	4.90	
Е	5.80	6.20	6.00	
E1	3.80	3.90	3.85	
E0	3.80	4.00	3.90	
е			1.27	
h			0.35	
٦	0.40	1.27		
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-8 (Standard B)



Dimensions	Value (in mm)		
С	1.27		
Х	0.802		
X1	4.612		
Υ	1.505		
Y1	6.50		



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